





An ISO/TS 16949, ISO 9001 and ISO 14001 Certified Company

PNP SILICON PLANAR EPITAXIAL TRANSISTORS

CP500 / 501 / 502 CP503 / 504

TO-92 Plastic Package



General Purpose Audio Transistors

Complementary CN300 series

ABSOLUTE MAXIMUM RATINGS

DESCRIPTION	SYMBOL	CP500	CP501	CP502	CP503	CP504	UNITS
Collector Base Voltage	V_{CBO}	25	35	35	45	70	V
Collector Emitter Voltage	V_{CEO}	25	35	35	45	70	V
Emitter Base Voltage	V_{EBO}		V				
Peak Pulse Current	I _C		mA				
Base Current	I_{B}	100					mA
Power Dissipation @ T _a =25°C	P_{D}	300					
Operating and Storage Junction Temperature Range	T_{j},T_{stg}	- 65 to +150					°C

ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
Collector Cut Off Current	I _{CBO}	$V_{CB}=V_{CB}$ (max)		200	nA
Emitter Cut Off Current	I _{EBO}	$V_{EB}=4V$, $I_C=0$		200	nA
Collector Emitter Voltage	V_{CEO}	$I_C=1$ mA, $I_B=0$			
		CP500	25		V
		CP501/CP502	35		V
		CP503	45		V
		CP504	70		V
Collector Emitter Saturation Voltage	*V _{CE (sat)}	$I_C=50$ mA, $I_B=5$ mA			V
		CP500/503		0.35	V
		CP501/502		0.25	V
		CP504		0.6	V
Base Emitter Saturation Voltage	*V _{BE (sat)}	$I_C=10mA$, $I_B=1mA$	0.65	1.0	V
DC Current Gain	*h _{FE}	I _C =100μA, V _{CE} =6V CP502	20		
		$I_C=10$ mA, $V_{CE}=6$ V			
		CP500/501/503/504	50	300	
		CP502	100	300	
		$I_C=50$ mA, $V_{CE}=6$ V	50		

^{*}Pulse Condition: Pulse Width = 300ms, Duty Cycle $\leq 2\%$.

PNP SILICON PLANAR EPITAXIAL TRANSISTORS

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CP500 / 501 / 502 CP503 / 504

TO-92

Plastic Package

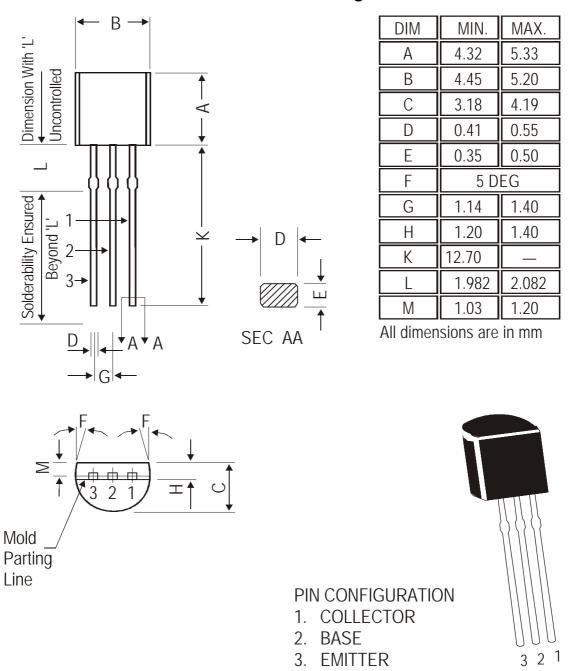
ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

DYNAMIC CHARACTERISTICS

DINAMIC CHARACTERISTICS					
DESCRIPTION	SYMBOL TEST CONDITION MIN		MAX	UNITS	
Output Capacitance	C _{obo}	V_{CB} =6V, I_E =0, f=1MHz		6	pF
Noise Figure	N _F	V_{CE} =6V, I_{C} =100μA, f=1KHz, R_{s} =1.5k Ω		7	dB
Transition Frequency	f⊤	V _{CE} =6V, I _C =10mA, f=100MHz	150		MHz

TO-92 Plastic Package

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The TO-92 Package, Tape and Ammo Pack Drawings are correct as on the date of issue/revision of this Data Sheet.

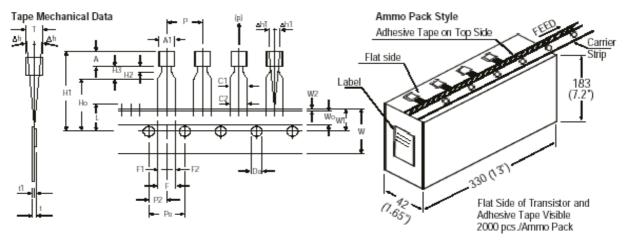
The currently valid dimensions and information, may please be confirmed from the TO-92 Drawing in the Packages and Packing Section of the Product Catalogue.

Packing Details

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	GrWt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

TO-92 Plastic Package

TO-92 Tape and Ammo Pack



All dimensions are in mm

		SPECIFICATION			ION	
ITEM	SYMBOL	MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.45		5.20		NOTES
BODY HEIGHT	A	4.32		5.33		1. Maximum alignment deviation
BODY THICKNESS	T	3.18		4.19		leads will not to be greater tha
PITCH OF COMPONENT	Р		12.7		± 1.0	2. Maximum non-cumulative vari
*1FEED HOLE PITCH	Po		12.7		± 0.3	between tape feed holes shall
*2 FEED HOLE CENTRE TO						exceed 1 mm in 20 pitches.
COMPONENT CENTRE	P2		6.35		± 0.4	Holddown tape will not exceed
DISTANCE BETWEEN OUTER	_		- 00		+ 0.6	the edge(s) of carrier tape and
LEADS	F		5.08		- 0.2	shall be no exposure of adhes
*3 COMPONENT ALIGNMENT SIDE VIEW	Δh		0	1.0		4. There will be no more than the
*4 COMPONENT ALIGNMENT FRONT VIEW	∆h1		0	1.3		consecutive missing compone
TAPE WIDTH	W		18		± 0.5	tape.
HOLD-DOWN TAPE WIDTH	Wo		6		± 0.2	5. A tape trailer, having at least the
HOLE POSITION	W1		9		+ 0.7	holes are provided after the la component in a tape.
					- 0.5	l ' '
HOLD-DOWN TAPE POSITION	W2	0.0		0.7		Splices should not interfere wi sprocket feed holes.
LEAD WIRE CLINCH HEIGHT	Ho		16		± 0.5	sprocket leed notes.
COMPONENT HEIGHT	H1			24.0		
LENGTH OF SNIPPED LEADS	L			11.0		
FEED HOLE DIAMETER	Do		4		± 0.2	REMARKS
*5 TOTAL TAPE THICKNESS	t			1.2		*1 Cumulative pitch error 1.0 mm
LEAD - TO - LEAD DISTANCE	F1, F2	2.40		2.70	- 0.1	
STAND OFF	H2	0.45		1.45	- 0.1	*2 To be measured at bottom of o
CLINCH HEIGHT	H3			3.0		*3 At top of body
LEAD PARALLELISM	C1 - C2			0.22		*4 At top of body
PULL - OUT FORCE	(p)	6N				*5 t1 0.3 – 0.6 mm

- n between ian 0.2mm.
- riation all not
- ed beyond ıd there sive.
- ree (3) ients in a
- three feed ast
- vith the
- m/20 pitch
- clinch

Customer Notes

CP500 / 501 / 502 CP503 / 504

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Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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